

Pin Definitions

Pin Number	Pin Name	Description
1	V _{DD1}	Supply Voltage to Channel-A detector IC and Channel-B buffer IC
2	V _{OA}	Output Voltage from Channel-A detector IC
3	V _{INB}	Input Voltage to Channel-B buffer IC
4	GND ₁	Ground for Channel-A detector IC and Channel-B buffer IC
5	GND ₂	Ground for Channel-A buffer IC and Channel-B detector IC
6	V _{OB}	Output Voltage from Channel-B detector IC
7	V _{INA}	Input Voltage to Channel-A buffer IC
8	V _{DD2}	Supply Voltage to Channel-A buffer IC and Channel-B detector IC

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Units
T _{STG}	Storage Temperature	-40 to +125	°C
T _{OPR}	Operating Temperature	-40 to +110	°C
T _J	Junction Temperature	-40 to +130	°C
T _{SOL}	Lead Solder Temperature (Refer to Reflow Temperature Profile)	260 for 10sec	°C
V _{DD1} , V _{DD2}	Supply Voltage	0 to 6.0	V
V _{IA} , V _{IB}	Input Voltage	-0.5 to VDD+0.5	V
I _{IA} , I _{IB}	Input DC Current	-10 to +10	μA
V _{OA} , V _{OB}	Output Voltage	-0.5 to VDD+0.5	V
I _{OA} , I _{OB}	Average Output Current	10	mA
PD _I	Input Power Dissipation ⁽¹⁾	60	mW
PD _O	Output Power Dissipation ⁽¹⁾	60	mW

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
T _A	Ambient Operating Temperature	-40	+110	°C
V _{DD1} , V _{DD2}	Supply Voltages (3.3V Operation) ⁽²⁾	3.0	3.6	V
	Supply Voltages (5.0V Operation) ⁽²⁾	4.5	5.5	V
V _{IH}	Logic High Input Voltage	2.0	V _{DD}	V
V _{IL}	Logic Low Input Voltage	0	0.8	V
t _r , t _f	Input Signal Rise and Fall Time		1.0	ms

Isolation Characteristics

Apply over all recommended conditions, typical value is measured at $T_A = 25^\circ\text{C}$

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	freq = 60Hz, $t = 1.0\text{min}$, $I_{\text{I-O}} \leq 10\mu\text{A}^{(3)(4)}$	3750			Vac_{RMS}
R_{ISO}	Isolation Resistance	$V_{\text{I-O}} = 500\text{V}^{(3)}$	10^{11}			Ω
C_{ISO}	Isolation Capacitance	$V_{\text{I-O}} = 0\text{V}$, freq = 1.0MHz ⁽³⁾		0.2		pF

Electrical Characteristics

$T_A = -40^\circ\text{C}$ to $+110^\circ\text{C}$, $3.0\text{V} \leq V_{\text{DD}} \leq 5.5\text{V}$, unless otherwise specified.

Apply over all recommended conditions, typical value is measured at $V_{\text{DD1}} = V_{\text{DD2}} = +3.3\text{V}$, $T_A = 25^\circ\text{C}$

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$I_{\text{DD1L}}, I_{\text{DD2L}}$	Logic Low Supply Current	$V_{\text{IA}}, V_{\text{IB}} = 0\text{V}$		5.8	8.0	mA
$I_{\text{DD1H}}, I_{\text{DD2H}}$	Logic High Supply Current	$V_{\text{IA}}, V_{\text{IB}} = V_{\text{DD}}$		2.5	4.0	mA
$I_{\text{IA}}, I_{\text{IB}}$	Input Current		-10		+10	μA
V_{OH}	Logic High Output Voltage	$I_{\text{O}} = -20\mu\text{A}$, $V_{\text{DD}} = 3.3\text{V}$, $V_{\text{I}} = V_{\text{IH}}$	3.2	3.3		V
		$I_{\text{O}} = -4\text{mA}$, $V_{\text{DD}} = 3.3\text{V}$, $V_{\text{I}} = V_{\text{IH}}$	3.0	3.1		V
		$I_{\text{O}} = -20\mu\text{A}$, $V_{\text{DD}} = 5\text{V}$, $V_{\text{I}} = V_{\text{IH}}$	4.9	5.0		V
		$I_{\text{O}} = -4\text{mA}$, $V_{\text{DD}} = 5\text{V}$, $V_{\text{I}} = V_{\text{IH}}$	4.7	4.8		V
V_{OL}	Logic Low Output Voltage	$I_{\text{O}} = 20\mu\text{A}$, $V_{\text{DD}} = 3.3\text{V}$ or 5V , $V_{\text{I}} = V_{\text{IL}}$		0	0.1	V
		$I_{\text{O}} = 4\text{mA}$, $V_{\text{DD}} = 3.3\text{V}$ or 5V , $V_{\text{I}} = V_{\text{IL}}$		0.26	0.6	V

Switching Characteristics

$T_A = -40^\circ\text{C}$ to $+110^\circ\text{C}$, $3.0\text{V} \leq V_{DD} \leq 5.5\text{V}$, unless otherwise specified.

Apply over all recommended conditions, typical value is measured at $V_{DD1} = V_{DD2} = +3.3\text{V}$, $T_A = 25^\circ\text{C}$

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Data Rate					15	Mbit/s
t_{PHL}	Propagation Delay Time to Logic Low Output	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}$		37	60	ns
t_{PLH}	Propagation Delay Time to Logic High Output	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}$		40	60	ns
PWD	Pulse Width Distortion, $ t_{PHL} - t_{PLH} $	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}^{(5)}$		3	15	ns
$t_{PSK(CC)}$	Channel-Channel Skew	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}^{(6)}$		12	25	ns
$t_{PSK(PP)}$	Part-Part Skew	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}^{(7)}$			30	ns
t_R	Output Rise Time (10% to 90%)	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}$		6.5		ns
t_F	Output Fall Time (90% to 10%)	$PW = 66.7\text{ns}$, $C_L = 15\text{pF}$		6.5		ns
$ CM_H $	Common Mode Transient Immunity at Output High	$V_I = V_{DD1}$, $V_O > 0.8V_{DD1}$, $V_{CM} = 1000\text{V}^{(8)}$	20	40		kV/ μs
$ CM_L $	Common Mode Transient Immunity at Output Low	$V_I = 0\text{V}$, $V_O < 0.8\text{V}$, $V_{CM} = 1000\text{V}^{(8)}$	20	40		kV/ μs

Notes:

1. No derating required.
2. $0.1\mu\text{F}$ bypass capacitor must be connected between Pin 1 and 4, and 5 and 8. The capacitors should be kept close to the supply pins.
3. Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
4. $3,750\text{ VAC}_{\text{RMS}}$ for 1 minute duration is equivalent to $4,500\text{ VAC}_{\text{RMS}}$ for 1 second duration.
5. PWD is equal to the magnitude of the worst case difference in t_{PHL} and/or t_{PLH} that will be seen for one channel switching, while holding the other channel output at a low or high state, or while both channels are in synchronous data transmission mode.
6. $t_{PSK(CC)}$ is equal to the magnitude of the worst case difference in t_{PHL} and/or t_{PLH} that will be seen between the two channels within a single device.
7. $t_{PSK(PP)}$ is equal to the magnitude of the worst case difference in t_{PHL} and/or t_{PLH} that will be seen between any two units from the same manufacturing date code that are operated at same case temperature, at same operating conditions, with equal loads.
8. Common mode transient immunity at output high is the maximum tolerable positive dV_{cm}/dt on the leading edge of the common mode impulse signal, V_{cm} , to assure that the output will remain high. Common mode transient immunity at output low is the maximum tolerable negative dV_{cm}/dt on the trailing edge of the common pulse signal, V_{cm} , to assure that the output will remain low.

Typical Performance Curves

Fig. 1 Typical Output Voltage vs. Input Voltage (Channel A & B)

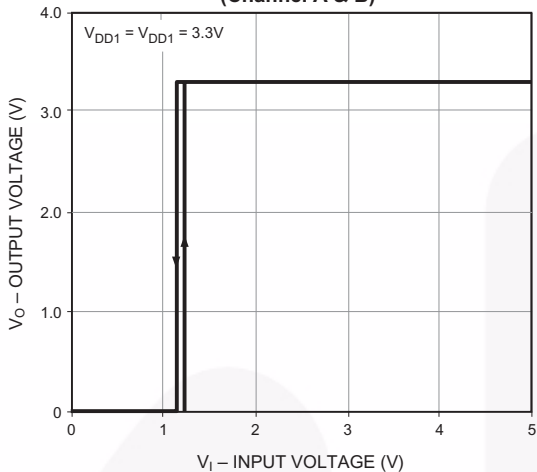


Fig. 2 Typical Input Voltage Switching Threshold vs. Input Supply Voltage (Channel A & B)

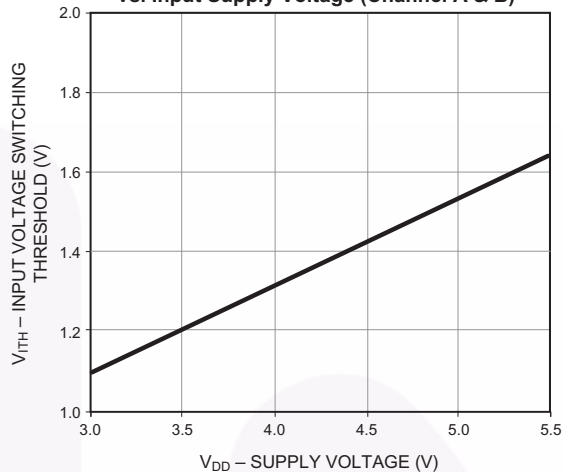


Fig. 3 Typical Propagation Delay vs. Ambient Temperature (Channel A & B)

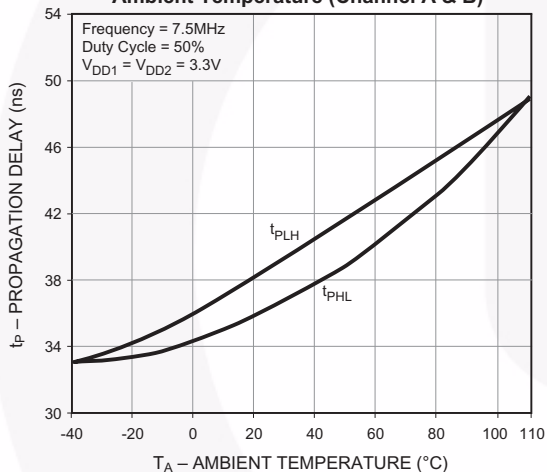


Fig. 4 Typical $t_{PHL} - t_{PLH}$ vs. Ambient Temperature (Channel A & B)

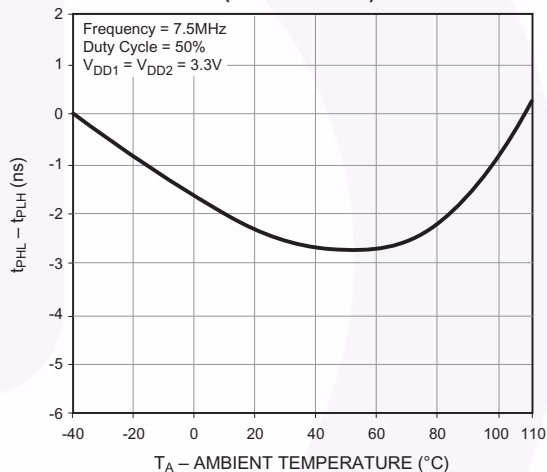


Fig. 5 Typical Rise Time vs. Ambient Temperature (Channel A & B)

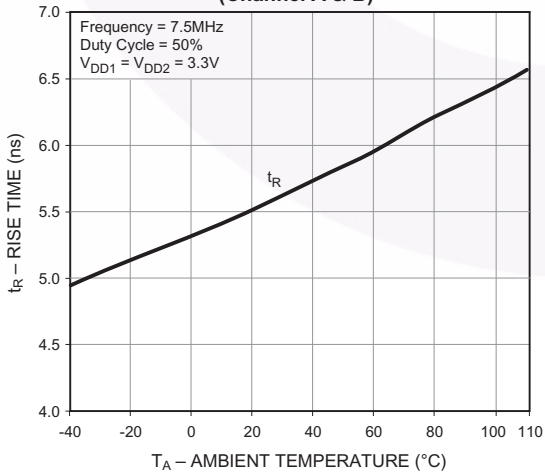
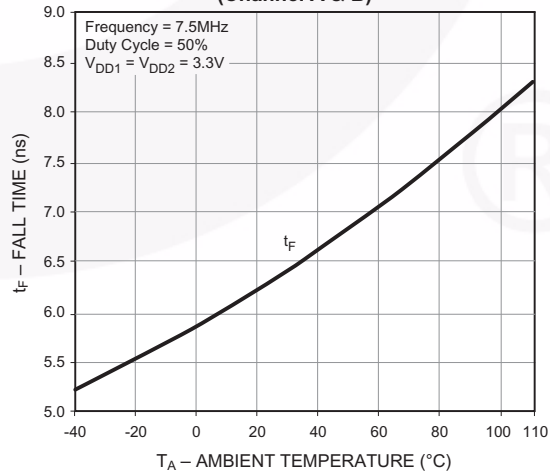


Fig. 6 Typical Fall Time vs. Ambient Temperature (Channel A & B)



Typical Performance Curves (Continued)

Fig. 7 Typical Propagation Delay vs. Output Load Capacitance (Channel A & B)

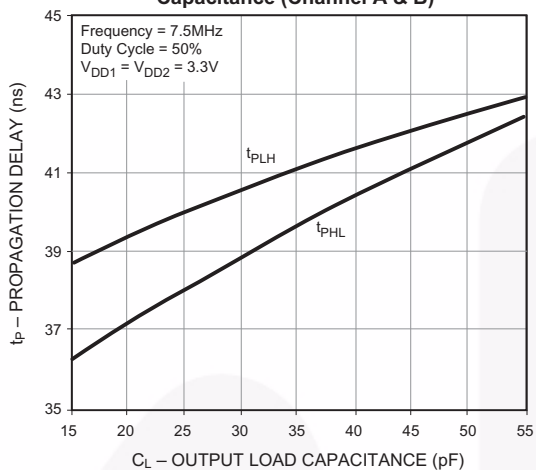


Fig. 8 Typical $t_{PHL} - t_{PLH}$ vs. Output Load Capacitance (Channel A & B)

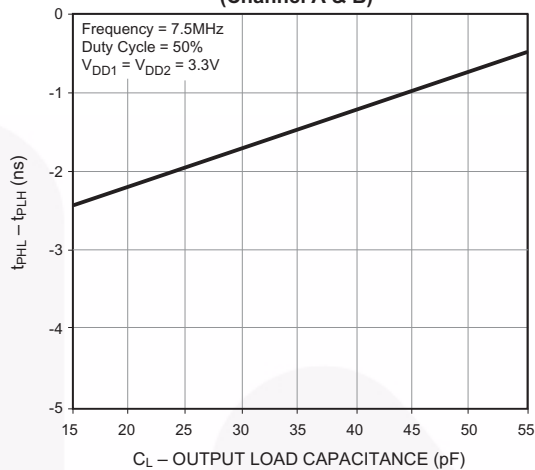


Fig. 9 Typical Rise Time vs. Output Load Capacitance (Channel A & B)

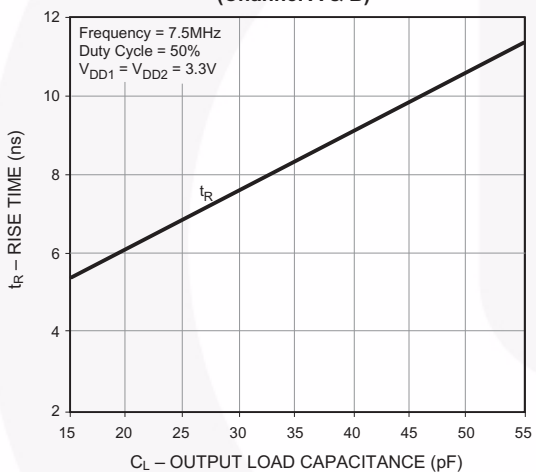
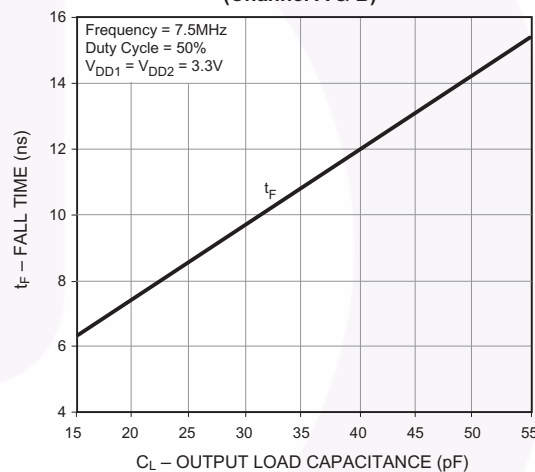
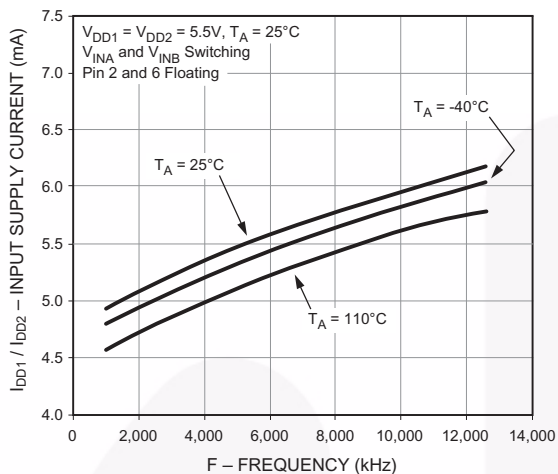
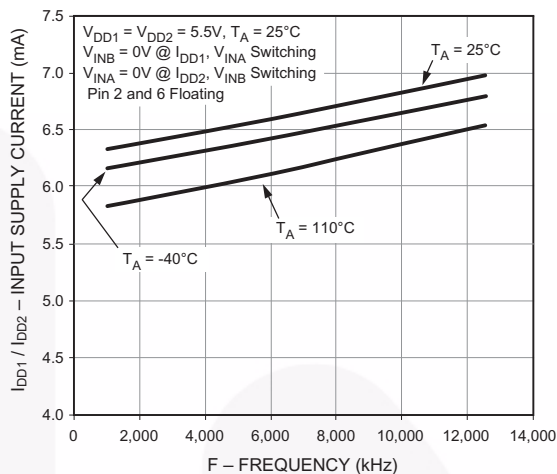
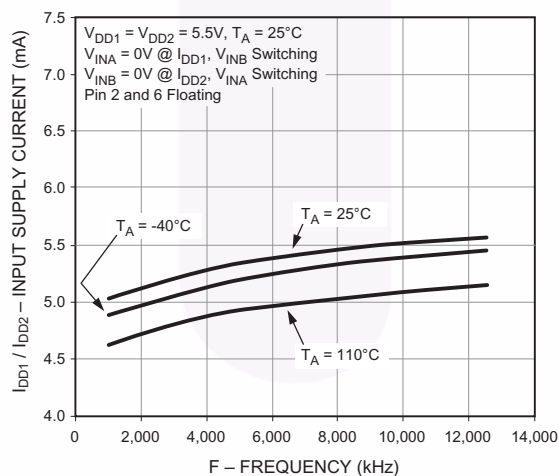


Fig. 10 Typical Fall Time vs. Output Load Capacitance (Channel A & B)



Typical Performance Curves (Continued)

Fig. 11a Typical I_{DD1}/I_{DD2} Supply Current vs. FrequencyFig. 11b Typical I_{DD1}/I_{DD2} Supply Current vs. FrequencyFig. 11c Typical I_{DD1}/I_{DD2} Supply Current vs. Frequency

Test Circuits

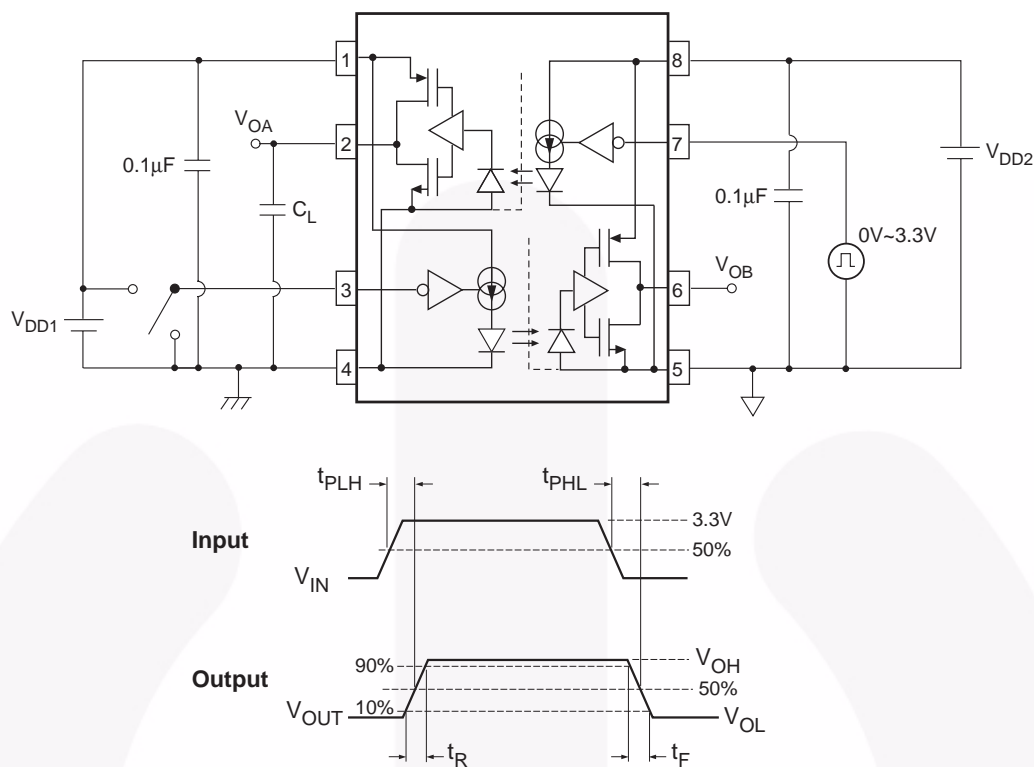


Figure 11. Test Circuit for Propagation Delay Time and Rise Time, Fall Time

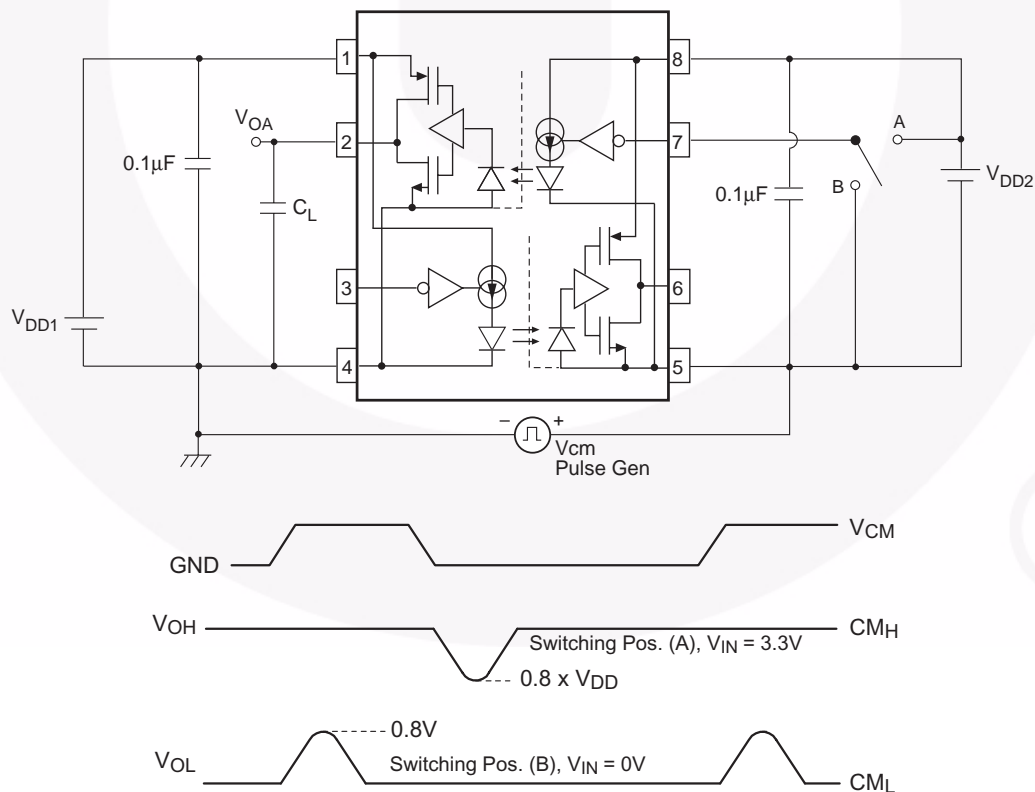
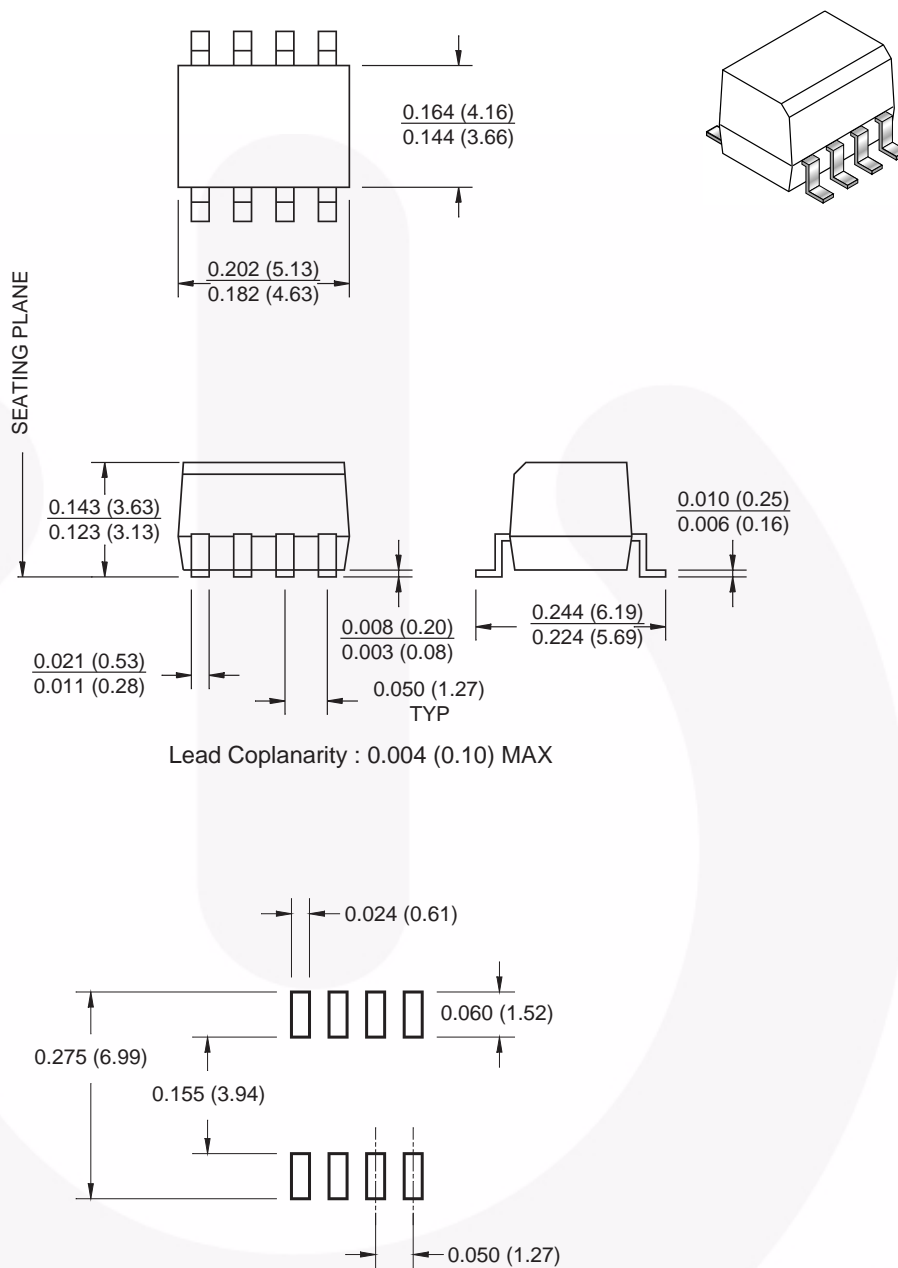


Figure 12. Test Circuit for Instantaneous Common Mode Rejection Voltage

Small Outline Package Dimensions

**Note:**

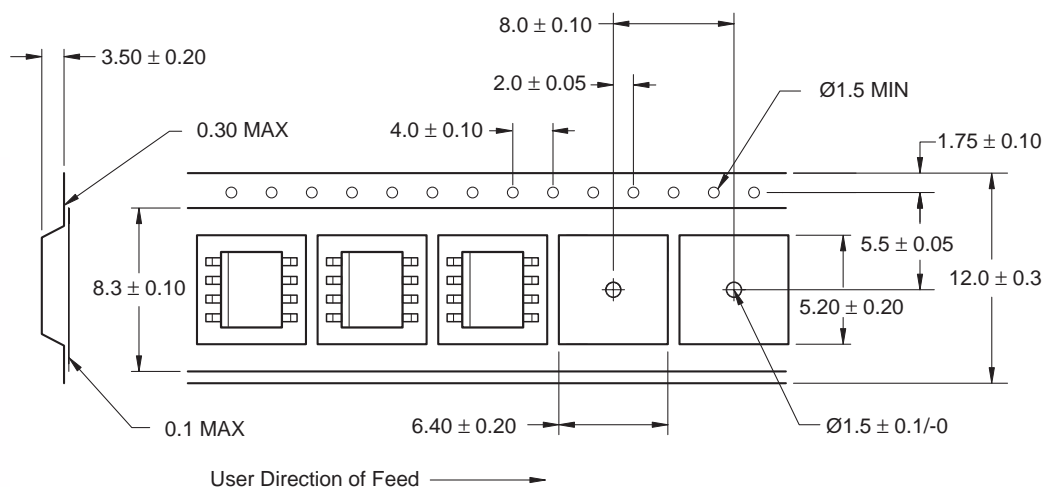
All dimensions are in millimeters.

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Carrier Tape Specification



Note:

All dimensions are in millimeters.

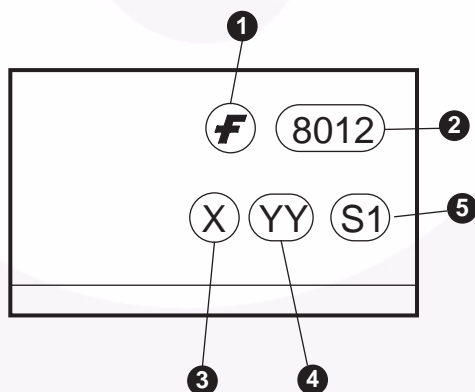
Ordering Information

Option	Order Entry Identifier	Description
No Suffix	FOD8012	Small outline 8-pin, shipped in tubes (50 units per tube)
R2	FOD8012R2	Small outline 8-pin, tape and reel (2,500 units per reel)



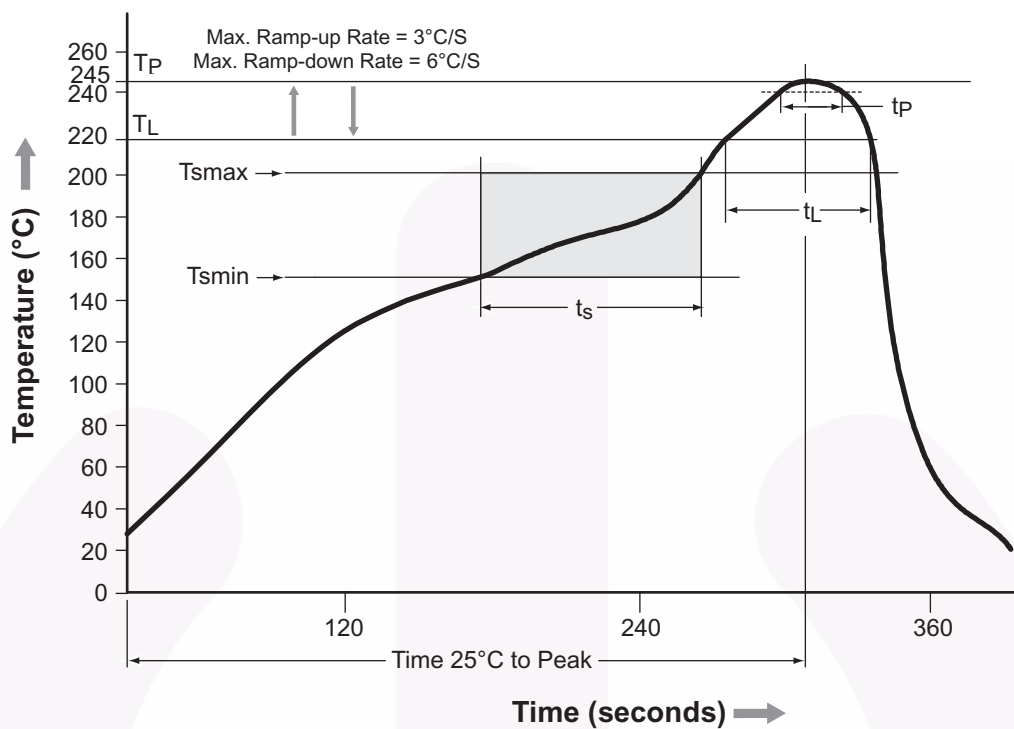
All packages are lead free per JEDEC: J-STD-020B standard.

Marking Information



Definitions	
1	Fairchild logo
2	Device number
3	One digit year code, e.g., '8'
4	Two digit work week ranging from '01' to '53'
5	Assembly package code

Reflow Profile








Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60–120 seconds
Ramp-up Rate (t _L to t _p)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60–150 seconds
Peak Body Package Temperature	245°C +0°C / –5°C
Time (t _p) within 5°C of 245°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.



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		Sync-Lock™	

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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